Mitsubishi Materials Corporation to Exhibit at the 2024 IEEE 74th Electronic Components and Technology Conference (ECTC), Booth #506!

Mitsubishi Materials Corporation is thrilled to announce our participation in the 2024 IEEE 74th Electronic Components and Technology Conference (ECTC), alongside our subsidiary, Mitsubishi Materials USA Corporation. This premier international event will be held in Denver, CO, from May 28 to May 31, 2024.

Under our commitment "For people, society and the earth, circulating resources for a sustainable future", Mitsubishi Materials Corporation will showcase our latest advancements in low alpha tin-silver plating chemistry and nanoporous Cu fine pitch bonding technologies for next-generation advanced interconnections.

Key highlights include:

Low Alpha Pb-Free Solder Plating Solution and Anode: We will present our latest low alpha Pb-free solder products for various bump formations (Sn and SnAg for C4 bump, Cu pillar, and micro bump). Solder bump plating plays a crucial role in advanced packaging, and Mitsubishi Materials leads the industry with over 20 years of experience, commanding over 60% of the global market share!

Nanoporous Cu Plating: We will showcase our latest innovation in nanoporous Cu plating technology for next-generation advanced interconnections.

Semiconductor-Related Products: Explore our cutting-edge semiconductor materials, including AuSn alloy paste and large square Si substrate materials.

Visit our **booth #506** to engage with our experts and learn more about our contributions to the future of electronic components and technology. For additional information and conference registration, please visit the IEEE ECTC website.

2024 IEEE 74th Electronic Components and Technology Conference https://ectc.net/index.cfm Mitsubishi Materials Booth #506

CONFERENCE & EXHIBITION LOCATION: Gaylord Rockies Resort & Convention Center 6700 North Gaylord Rockies Boulevard Aurora, Colorado, USA, 80019

EXHIBITION HOURS: Wednesday, May 29/ 9:00am–12:30pm, 2:00 –6:30pm Thursday, May30/ 9:00am–12:30pm,2:00 -4:00pm



